

SOLAR

InWaClean




Inline-Wafer Cleaning

The InWaClean removes slurry and sawing residues from separated wafers in a physical-chemical process.

Areas of application

- Final cleaning of precleaned and separated mono- and multicrystalline wafers
- Horizontal cleaning of rectangular silicon wafers
- Removal of slurry and silicon residues from a sawing process
- Removal of silicon residues from a diamond wire sawing process
- Main cleaning process with water and ultrasonic cleaning

Features and benefits

- The wafer is kept wet throughout the entire process until drying, in order to prevent the electrostatic bonding of particles
 - Ultrasonic cleaning employing various frequencies
 - No etching of wafer surface, thus best initial conditions for a variety of texturing processes
 - Modular design
 - Special roller construction reduces operating costs
 - Rinsing cascade reduces water consumption
 - Permanent temperature regulation and conductivity measurement
 - Feed and bleed function in all cleaning tanks
 - RENA AirChannelDryer technology
 - Integrated wafer-counters establish load and unload numbers, throughput, quality and material loss
 - Best service access to the process area from front and back
 - Environmentally friendly basic process, low chemical use, without need for neutralisation
 - Patented by RENA
- Optional:
- Connection to MES
 - Manual or automatic wafer removal via RENA VarioUnload system
 - Wafer tracking





Wafer Input



Wafer Transport



RENA.

Fully automated inline wafer cleaning

Technical Data InWaClean

Process	<ul style="list-style-type: none"> • Final cleaning and drying of pre-cleaned, rectangular silicon wafers • Ultrasonic cleaning at different frequencies • Optimised inline transport system for thin solar wafers • Rinsers connected as cascades to minimise water usage • Cleaning is supported by minimum quantity of cleaning chemicals 		
Dimensions	Multi-lane transport system	10570 x 2000 x 2200 mm (length x width x height)	
Throughput	Multi-lane transport system • Wafer size 156 mm	Multi up to 4000 wafers/h	Mono up to 3500 wafers/h
Wafer thickness	Proofed for 160 µm		
Media consumption	<ul style="list-style-type: none"> • DI water with 1 - 10 MOhm (1.0 - 0.1 µS/cm) • Cleaner Tegee InWaCleanerSi010 • Electricity 	1000 l/h	380 - 400V AC +5% 3Ph+N+PE, 50 Hz, 77 kW, 177 A